



Material Content Data Sheet



Sales Product Name		TLE4262G		Issued		29. August 2013			
MA#		MA000835042							
Package		PG-DSO-20-35		Weight*		478.18 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.136	0.66	0.66	6558	6558	
leadframe	inorganic material	phosphorus	7723-14-0	0.036	0.01		75		
	non noble metal	zinc	7440-66-6	0.143	0.03		299		
	non noble metal	iron	7439-89-6	2.862	0.60		5985		
wire	non noble metal	copper	7440-50-8	116.197	24.30	24.94	242998	249357	
	noble metal	gold	7440-57-5	0.318	0.07	0.07	665	665	
	encapsulation	organic material	carbon black	1333-86-4	0.700	0.15		1464	
plating	plastics	epoxy resin	-	32.192	6.73		67322		
	inorganic material	silicondioxide	60676-86-0	317.021	66.28	73.16	662975	731761	
	leadfinish	non noble metal	tin	7440-31-5	2.746	0.57	0.57	5742	5742
glue	noble metal	silver	7440-22-4	1.177	0.25	0.25	2461	2461	
*deviation	< 10%	plastics	epoxy resin	-	0.413	0.09		864	
		noble metal	silver	7440-22-4	1.239	0.26	0.35	2592	3456
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
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